

REMARKS

Claims 1-21 are pending and under consideration. Claims 1-20 are allowed.

Independent claim 21 recites a printed wiring board spaced from the electronic component to form a gap therebetween and a spacer selectively attached to the printed wiring board by an elastic deformation thereof to seal the gap. Thus, the sealed gap is between the electronic component and the printed wiring board.

The Examiner relies upon the O-ring 12 of Huffman as corresponding to the claimed spacer. The Examiner also relies upon the capacitor 4 and the circuit board 2 of Huffman as respectively corresponding to the claimed electronic component and printed wiring board. However, the O-ring 12 does not seal a gap between the capacitor 4 and circuit board 2. Instead, the O-ring 12 contacts the circuit board 2 and the mounting ring 10.

Accordingly, withdrawal of the rejection is requested.

There being no further outstanding objections or rejections, it is submitted that the application is in condition for allowance. An early action to that effect is courteously solicited.


Finally, if there are any formal matters remaining after this response, the Examiner is requested to telephone the undersigned to attend to these matters.

If there are any additional fees associated with filing of this Amendment, please charge the same to our Deposit Account No. 19-3935.

Respectfully submitted,

STAAS & HALSEY LLP

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By: 
Michael J. Badagliacca
Registration No. 39,099

1201 New York Avenue, NW, Suite 700
Washington, D.C. 20005
Telephone: (202) 434-1500
Facsimile: (202) 434-1501